

Delock Thermal Conductive Pad 70 x 20 x 0.75 mm for M.2 modules 3.0 W/mK

Description

This thermal conductive pad by Delock is suitable for heat dissipation, for example, on an M.2 module. The goal of the pad is to **improve performance and increase the service life** of the components.



Item no. 18473

EAN: 4043619184736

Country of origin: Taiwan,
Republic of China

Package: Zip poly bag

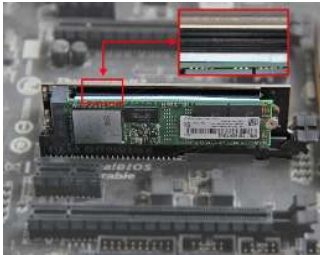
Technical details

- Thermal pad for heat dissipation
- Thermal conductivity: 3.0 W/mK
- Operating temperature: -60 °C ~ 180 °C
- Colour: grey
- Dimensions (LxWxH): ca. 70 x 20 x 0.75 mm

Package content

- 1 x thermal conductive pad

Images



Physical characteristics

Thermal conductivity:	3.0 W/mK
Length:	70 mm
Width:	20 mm
Height:	0.75 mm

Manufacturer information

Street	Beeskowdamm 13/15
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